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**SPACE PRODUCT ASSURANCE - THE
MANUAL SOLDERING OF HIGH-RELIABILITY
ELECTRICAL CONNECTIONS**

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EUROPÄISCHE NORM

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English version

**Space product assurance –
The manual soldering of high-reliability electrical connections**

Conformité pour les produits spatiaux -
Manuel de soudabilité des connexions
électriques de haute fiabilité

Raumfahrt-Produktsicherung –
Handlöten elektrischer Verbindungen
hoher Zuverlässigkeit

This European Standard was approved by CENELEC on 2004-04-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in two official versions (English, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Slovakia, Slovenia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

This European Standard has been prepared by the former CENELEC BTTF 91-3, Space equipment standardization, the work of which has been transferred by 113 BT to CENELEC TC 107X, Process management for avionics.

It is based on a previous version ¹⁾ originally prepared by the ECSS Product Assurance Working Group, reviewed by the ECSS Technical Panel and approved by the ECSS Steering Board. The European Cooperation for Space Standardization (ECSS) is a cooperative effort of the European Space Agency, National Space Agencies and European industry associations for the purpose of developing and maintaining common standards.

This European Standard is one of the series of space standards intended to be applied together for the management, engineering and product assurance in space projects and applications.

Requirements in this European Standard are defined in terms of what shall be accomplished, rather than in terms of how to organize and perform the necessary work. This allows existing organizational structures and methods to be applied where they are effective, and for the structures and methods to evolve as necessary without rewriting the standards.

The formulation of this European Standard takes into account the existing ISO 9000 family of documents.

The text of the draft was submitted to the formal vote and was approved by CENELEC as EN 50390 on 2004-04-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
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- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2007-04-01

¹⁾ ECSS-Q-70-08A.

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